

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAKAHITO HARADA	10/01/2015
RECEIVING PARTY DATA	
Name:	FUJI ELECTRIC CO., LTD.
Street Address:	1-1 TANABESHINDEN, KAWASAKI-KU,
City:	KAWASAKI-SHI,
State/Country:	JAPAN
Postal Code:	210-9530
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14877389
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	FUJ-275
NAME OF SUBMITTER:	MANABU KANESAKA
SIGNATURE:	/Manabu KANESAKA/
DATE SIGNED:	10/07/2015
Total Attachments: 1	
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ASSIGNMENT

For value received, I, Takahito HARADA having post office address at c/o FUJI ELECTRIC CO., LTD., 1-1 Tanabeshinden, Kawasaki-ku, Kawasaki-shi 210-9530, Japan hereby sell, assign and transfer to FUJI ELECTRIC CO., LTD. corporation existing under the laws of Japan located at 1-1 Tanabeshinden, Kawasaki-ku, Kawasaki-shi 210-9530, Japan and its successors, assigns, and legal representatives the entire right, title, and interest for all countries including the United States of America, in and to certain inventions relating to SEMICONDUCTOR MODULE described in application for Letters Patent of the United States, executed by me on this date, and all patents which may be granted therefor, and all divisions, reissues, continuations and extensions thereof, and authorize and request the Commissioner of Patents and Trademarks to issue all patents on said improvements or resulting therefrom to said Company as assignee of the entire interest, and covenant that I have full right so to do, and agree that I will communicate to said Company or its representatives any facts known to me respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees, to obtain and enforce proper protection for said invention in the United States.

Signature

Takahito Harada

Date

1st October 2015

Takahito HARADA